QE for Matter V1.0.0

Release Note

Thank you very much for using the QE for Matter V1.0.0, a QE (Quick and Effective Tool Solution) product of Renesas Solution Toolkit - Development Support Tool for Various Applications.

This release note covers product installation, restrictions, and so on. Please read this document before using the product.

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1. About QE for Matter

1.1 Summary

QE for Matter is a development assistance tool that streamlines Matter application development, enabling efficient and high-quality development through data model configuration and automated code generation. Using this tool, you can easily configure Matter clusters and attributes within the IDE and generate the required source code automatically.

1.2 Functions

The main functions are listed below:

1. Provides a guided and streamlined workflow for Matter application development
2. Enables easy configuration of Matter clusters, attributes, and endpoints within the IDE
3. Automatically generates Matter data model source code

1.3 Supported Environment

- Windows 11 (64-bit version)
- Renesas e^2 studio 2026-04.2
- RAFW Flexible Software Package 2.1.0

1.4 Supported Microcontrollers

- RA Family
  - RA6 Series: RA6W1, RA6W2

2. Installation and Uninstallation

2.1 Installing This Product

Use either of the following procedures to install this product.

2.1.1 Install from the "Renesas software installer" menu of e² studio

1. Start e² studio.
2. Select the “Renesas Views” - “Renesas Software Installer” menu of e² studio to open the “Renesas Software Installer” dialog box.
3. Select the “Renesas QE” and click the “Next >” button
4. Select the “QE for Matter (v1.0.0)” check box and click the “Finish” button.
5. Check that the “Renesas QE for Matter” check box is selected in the “Install” dialog box and click the “Next >” button.
6. Check that the “Renesas QE for Matter” check box is selected as the target of installation and click the “Next>” button.
7. After confirming the license agreements, if you agree to the license, select the “I accept the terms of the license agreements” radio button, and click the “Finish” button.
8. When the dialog box for selecting a trusted certificate appears, check the displayed certificate, and then click on the “Trust Selected” button to continue installation.
9. Restart the e² studio by following the instructions on the screen.
10. Start this product from the “Renesas Views” - “Renesas QE” menu of e² studio. For details about how to use this product, see the “Help” menu of e² studio.

2.1.2 Install using QE (zip file) downloaded from the Renesas website

1. Extract the downloaded zip file.
2. Start the e² studio.
3. Click on “Help”, and then click on the “Install New Software...” menu item to open the “Install” dialog box.
4. Click on the “Add...” button to open the “Add Repository” dialog box.
5. Click on the “Archive...” button, select the installation file (zip file under the QE-SegmentLCD folder) in the opened file selection dialog box, and then click on the “Open” button.
6. Click on the “Add” button in the “Add Repository” dialog box.
7. Expand the “Renesas QE” item shown in the “Install” dialog box, select the “Renesas QE for Matter” check box, and then click on the “Next>” button.
   *If you check off the “Contact all update sites during install to find required software” checkbox, you can shorten the installation time.
8. Confirm that the installation target is “Renesas QE for Matter”, and then click on the “Next>” button.
9. After checking the license, select the “I accept the terms of the license agreements” radio button if you agree it, and then click on the “Finish” button.
10. When the dialog box for selecting a trusted certificate appears, check the displayed certificate, and then click on the “Trust Selected” button to continue the installation.
11. Restart the e² studio by following the instructions on the screen.
12. Start this product from the “Renesas Views” - “Renesas QE” menu of the e² studio. For details about how to use this product, see the “Help” menu of e² studio.

2.2 Updating This Product

If you have already used this product, you can update it in the same way as the procedure for installation.

2.3 Uninstalling This Product

Follow the procedure below to uninstall this product.

1. Start the e² studio.
2. Select “Help -> About e² studio” to open the “About e² studio ” dialog box.
3. Click the “Installation Details” button to open the “e² studio Installation Details” dialog box.
4. Select “Renesas QE for Matter” displayed on the “Installed Software” tabbed page and click on the “Uninstall...” button to open the “Uninstall” dialog box.
5. Check the displayed information and click on the “Finish” button.
6. Restart the e² studio by following the instructions on the screen.

3. Notes / Restrictions

3.1 Usage Considerations

Please pay attention to the following items.

3.1.1 Notes on opening [Matter Workflow (QE)] view

The workflow cannot be opened if WebView2 Runtime is not installed on your PC.

[Workaround]

Download and install WebView2 (x64 version) from the Microsoft web page. (FAQ: 3000670)

3.1.2 Notes on opening [Matter ZAP Tool (QE)] view

When opening a .zap file, the Matter ZAP Tool (QE) view may fail to load Matter configuration information when both of the following conditions are met:

1. The required zcl and template JSON files defined in the .zap file does not exist.
2. A ZAP tool version earlier than v2025.10.23 is used.

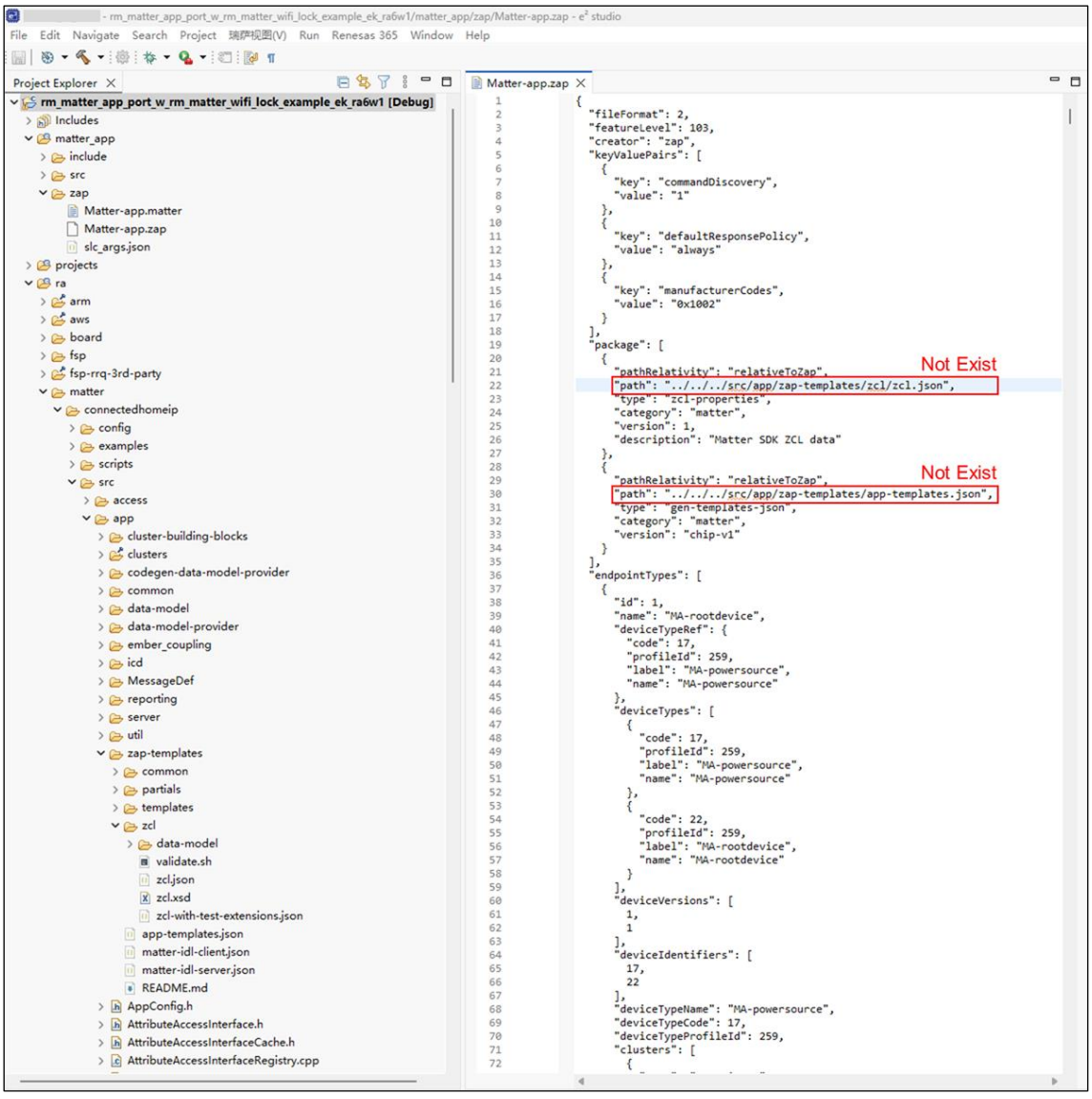

Figure 3-1 (1). Missing JSON files defined in .zap file

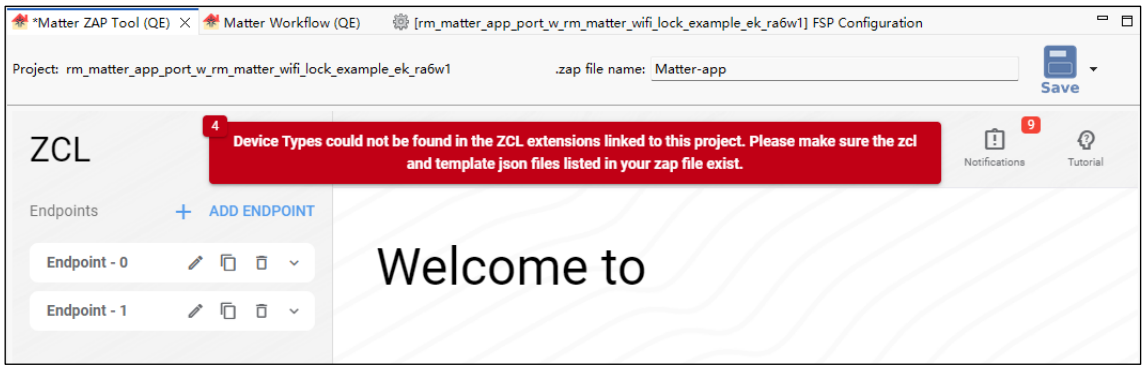

Figure 3-1 (2). Failed to load Matter configuration information

[Workaround]

Either of the following two workarounds can be used.

- Workaround 1:

  Use ZAP Tool v2025.10.23 or later.

- Workaround 2:

  Manually verify and update the zcl and template JSON files path defined in the .zap file, ensuring that it references an existing file.

3.1.3 Notes on configuring on the [Matter ZAP Tool (QE)] view

Configurations in the Matter ZAP Tool (QE) view are saved to the corresponding .zap file only after clicking the [Save] button.

In general, an asterisk (*) is displayed next to the view name when there are unsaved changes. However, in some cases, configuration changes may not trigger the asterisk. In such cases as well, click the [Save] button after completing the configuration to ensure that the latest settings are saved.

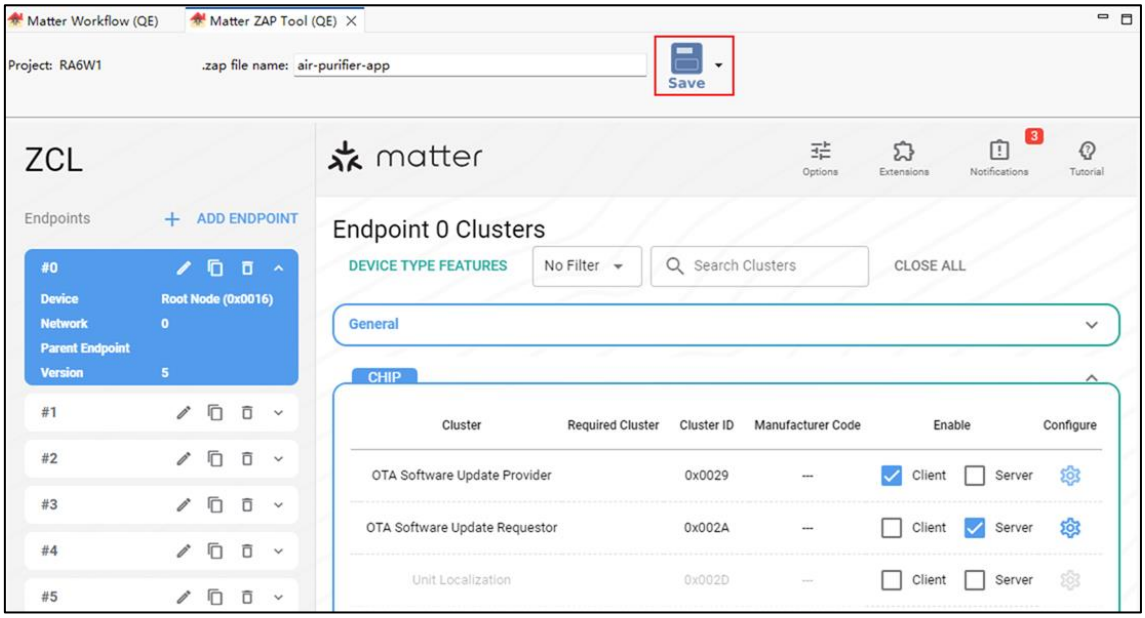

Figure 3-2. Save button on Matter ZAP Tool (QE) view

3.1.4 Notes on [Console] view

After clicking the [Generate C/C++ Code] button in the Matter Workflow (QE) view, a large amount of information is printed to the Console. When you subsequently click the [Save] button in the Matter ZAP Tool (QE) view, the hyperlink in the newly output message may not be displayed with the correct visual appearance. However, the hyperlink functionality is not affected, it is still clickable and works as expected.

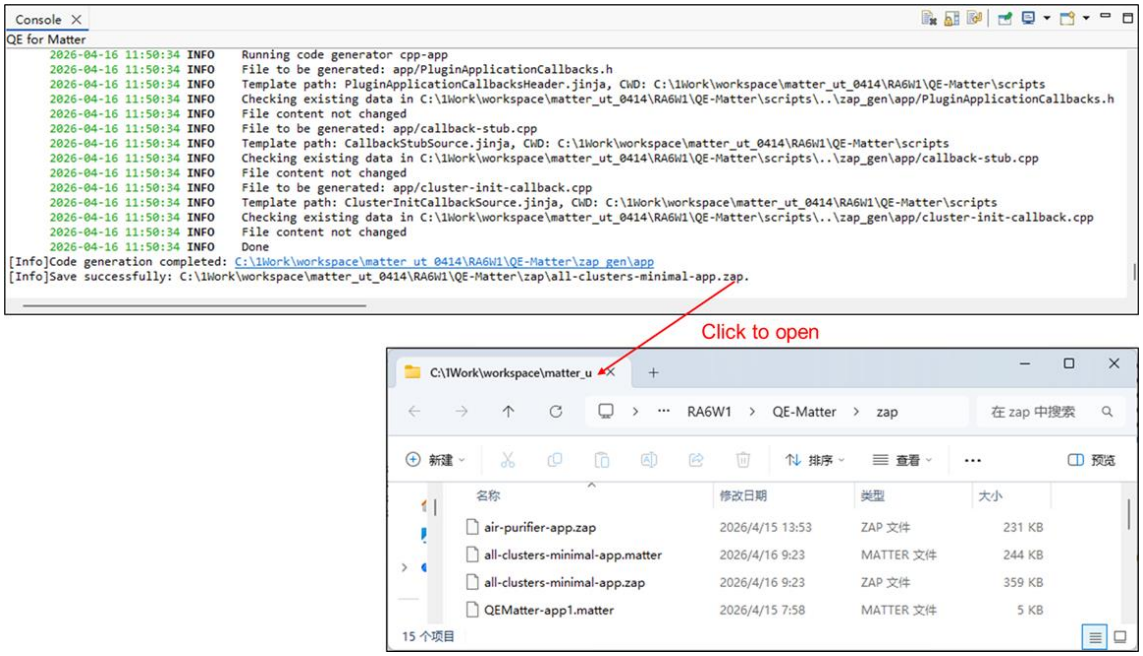

Figure 3-3 (1). Hyperlink displayed without visual styling but functioning correctly

[Workaround]

Clear the Console view before clicking the [Save] button.

After clearing the Console, hyperlink in the [Save] output can be displayed with correct visual appearance.

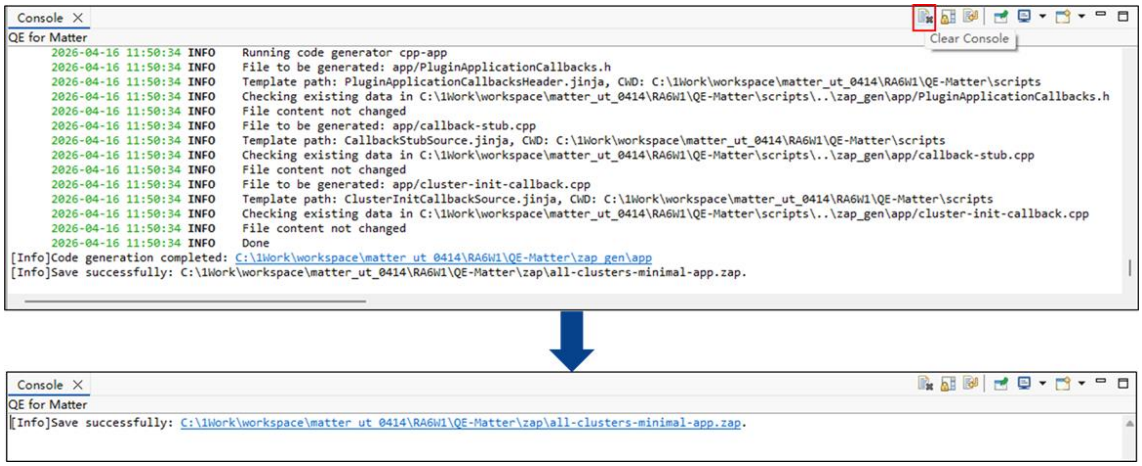

Figure 3-3 (2). Hyperlink displayed correctly after clearing the Console

3.2 Functional Restrictions

There is no restriction in QE for Matter V1.0.0.

4. About the Software Bill of Materials (SBOM)

For this release, a Software Bill of Materials (SBOM) is provided to describe the software components and OSS license information included in this product.

The SBOM is created in SPDX Lite format and is included in the zip archive distributed together with this release note.

Revision History

Rev.	Date	Description	
		Page	Summary
1.00	Jun.30.2026	-	First edition issued.

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

   A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.
2. Processing at power-on

   The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.
3. Input of signal during power-off state

   Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.
4. Handling of unused pins

   Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.
5. Clock signals

   After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.
6. Voltage application waveform at input pin

   Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).
7. Prohibition of access to reserved addresses

   Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.
8. Differences between products

   Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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